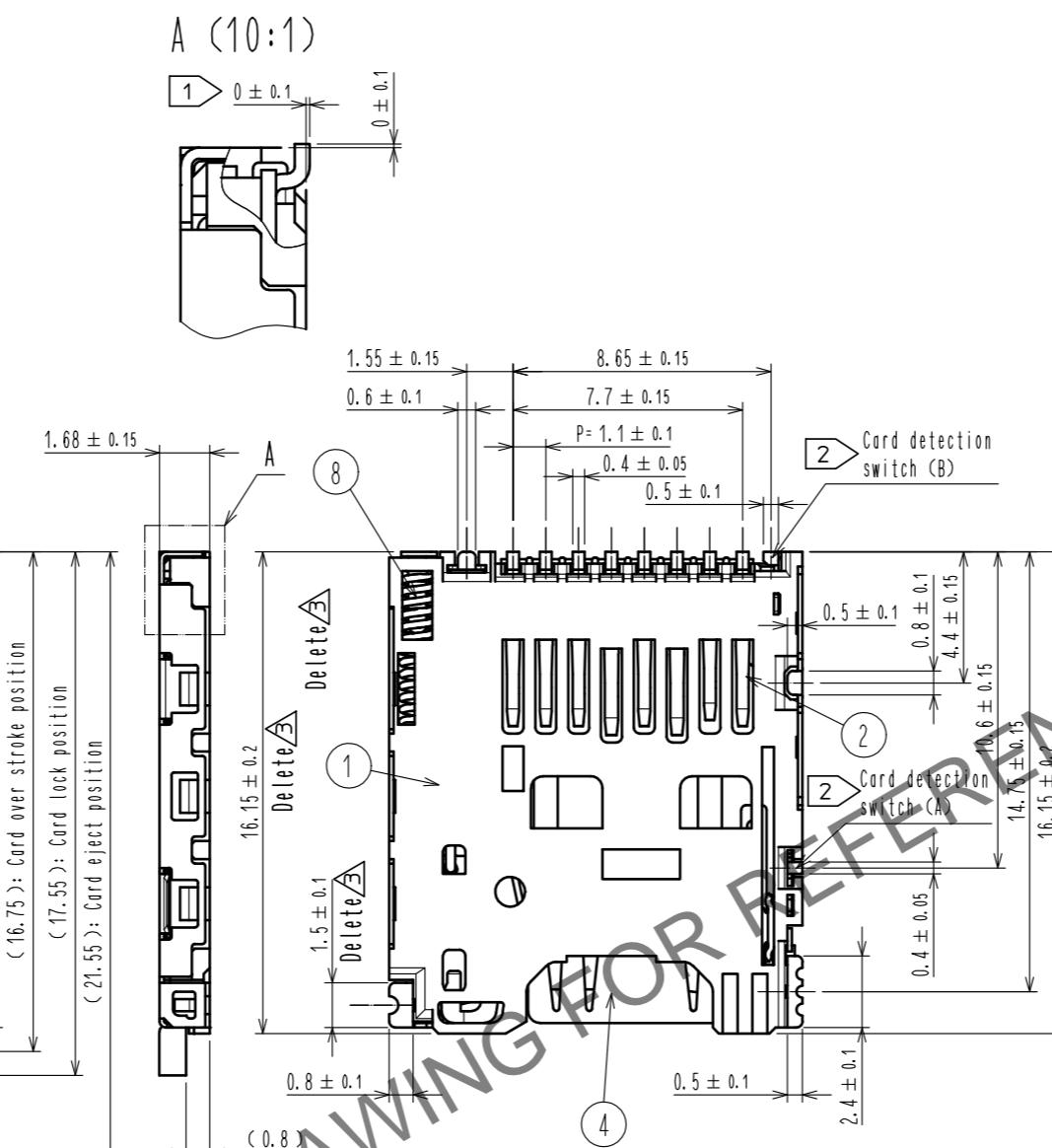
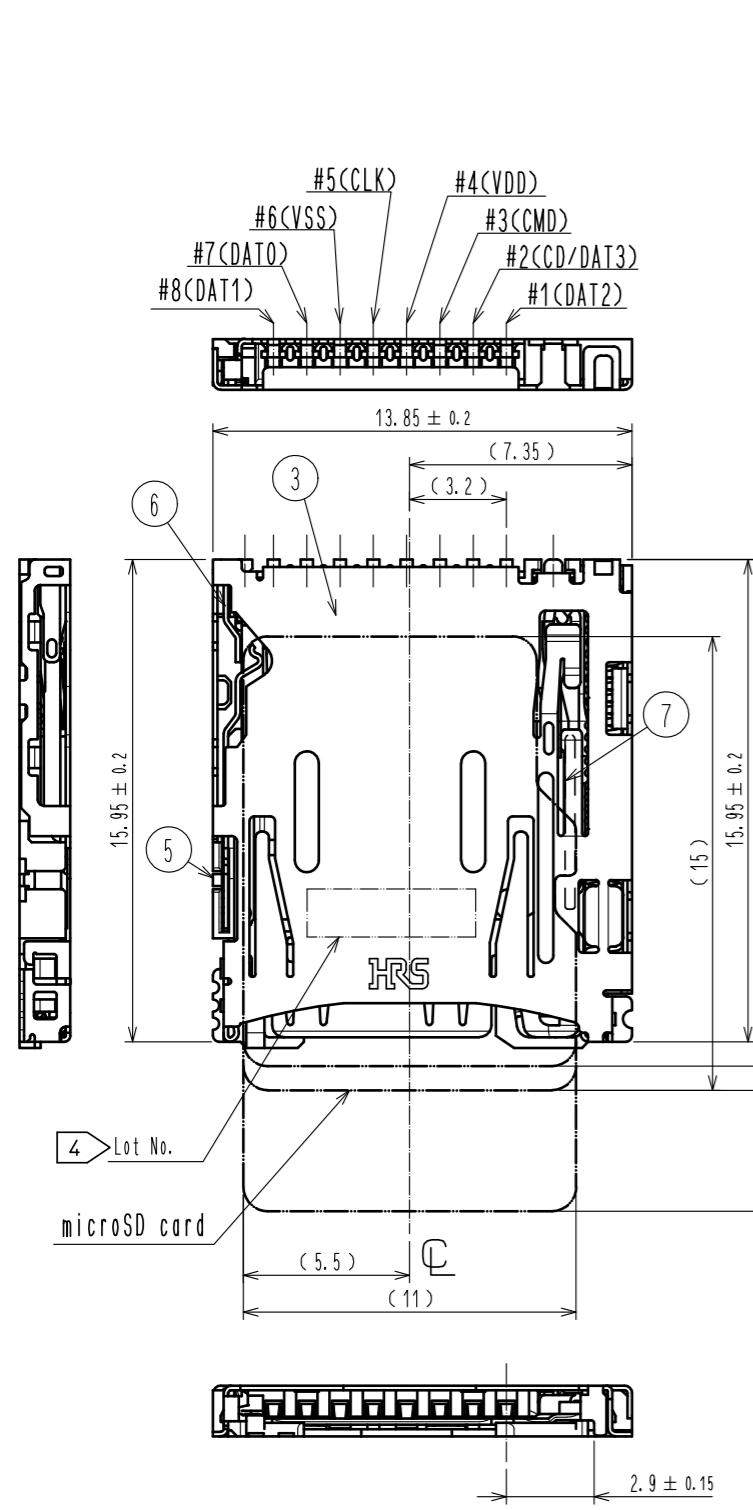


## 4 Manufacturing Date

Year		Month		Date					
Year	Symbol	Month	Symbol	Date	Symbol	Date	Symbol	Date	Symbol
2020	O	Jan.	A	1	1	11	B	21	M
2021	1	Feb.	B	2	2	12	C	22	N
2022	2	Mar.	C	3	3	13	D	23	P
2023	3	Apr.	D	4	4	14	E	24	Q
2024	4	May	E	5	5	15	F	25	R
2025	5	Jun.	F	6	6	16	G	26	S
2026	6	Jul.	G	7	7	17	H	27	T
2017	7	Aug.	H	8	8	18	J	28	U
2018	8	Sep.	I	9	9	19	K	29	V
2019	9	Oct.	J	10	A	20	L	30	W
		Nov.	K					31	X
		Dec.	I						

 Added handling instructions.



Notes 1 Co-planarity shall be 0.1mm max.

## 2 Card detection switch.

No card	Card inserted
Open 	Close 
(A) (B)	(A) (B)

  : No patterns are permitted in this oblique-hatched area.

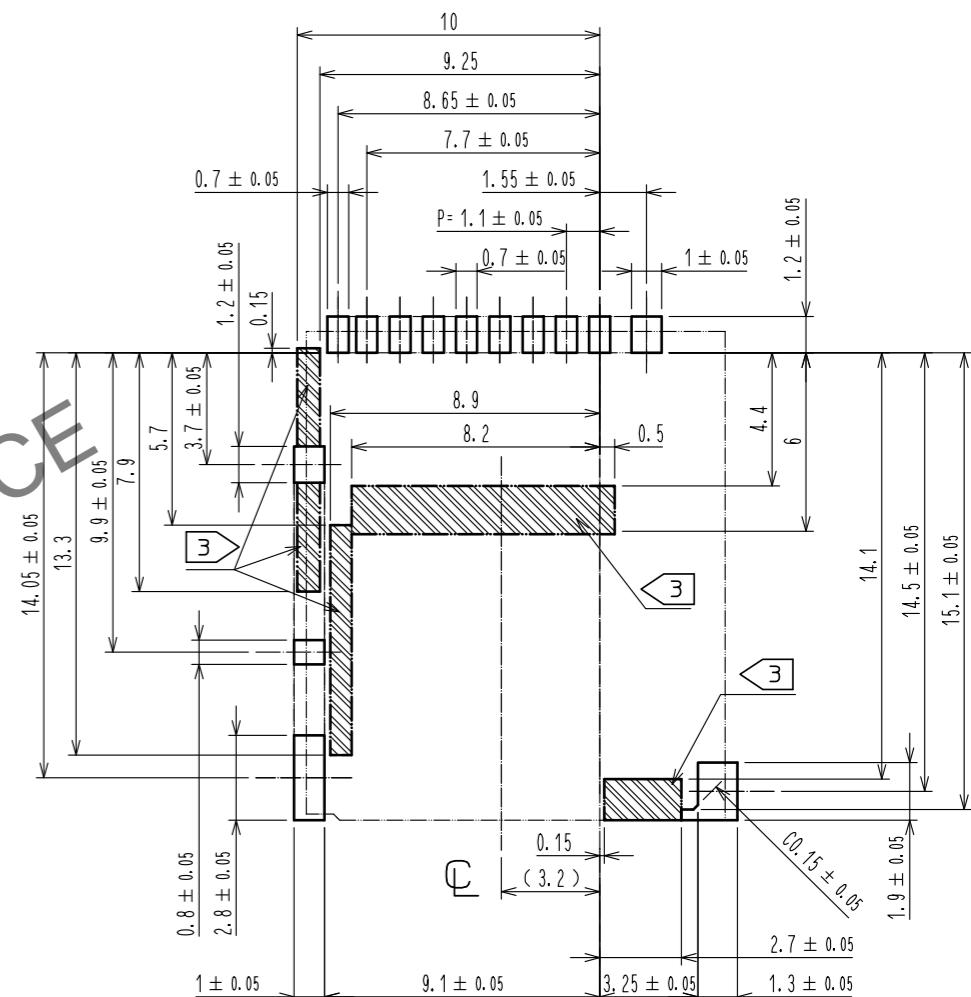
**4**) Lot. No. shall be indicated as shown.

e. g. : 9 A

Production Line : Line No.1  
Date : 17th  
Month : Jan.  
Year : 2019

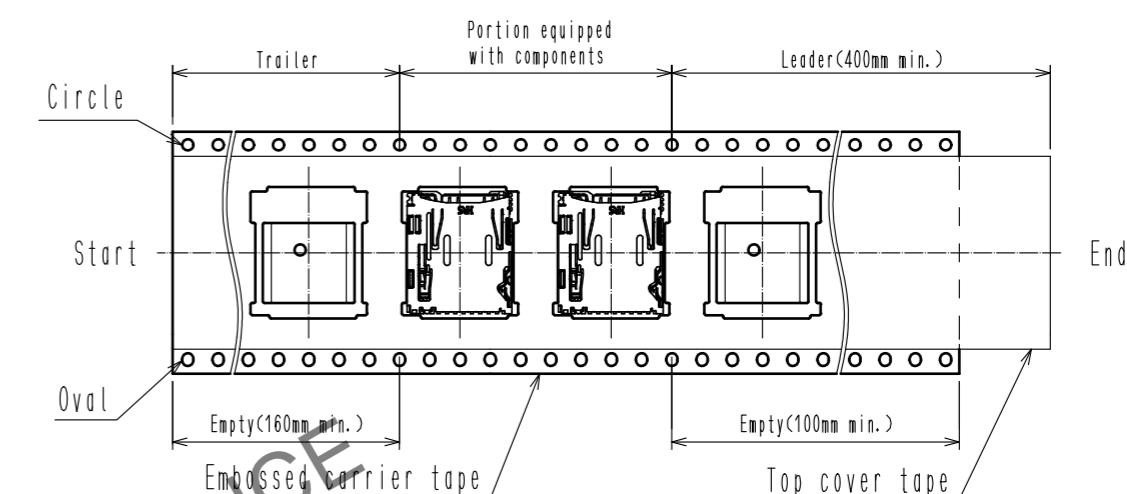
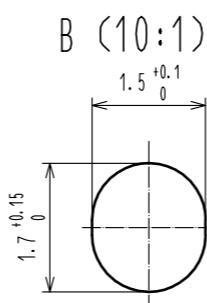
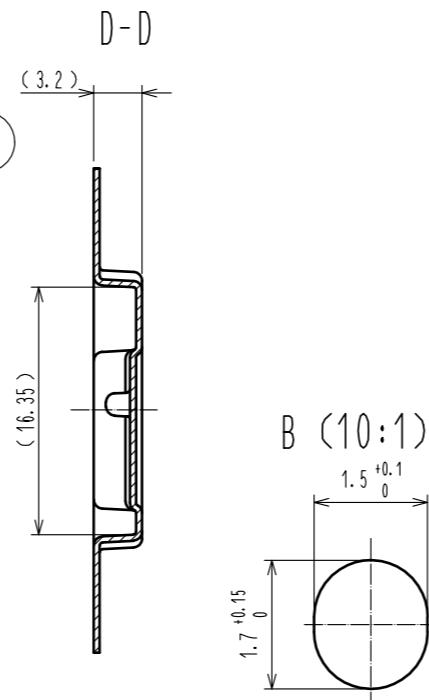
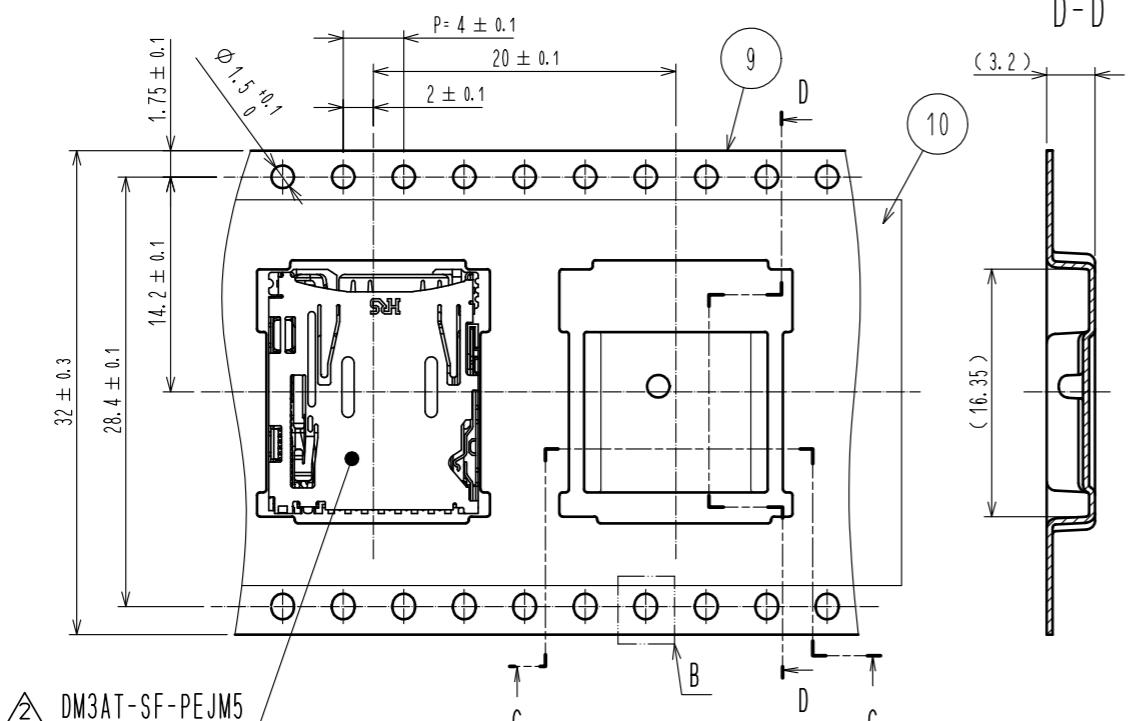
### Recommended PCB layout (mounting side)

② Metal mask thickness  $t=0.12\text{mm}$

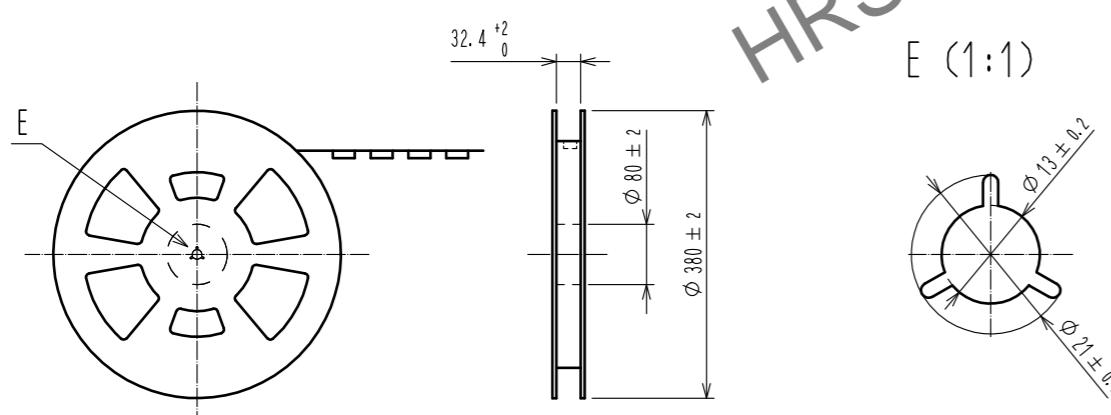


			10	Polyester			
4	Stainless steel		9	PS			
3	Stainless steel	Mounting area Ni $0.5\mu m$ +Au $0.03\mu m$	8	Stainless steel			
2	Phosphor bronze	Contact area Ni $3\mu m$ +Au $0.1\mu m$	7	Stainless steel			
		Mounting area Ni $3\mu m$ +Au $0.03\mu m$	5. 6	Phosphor bronze	Contact area Ni $1.5\mu m$ +Au $0.1\mu m$		
1	LCP	Black UL94V-0			Mounting area Ni $1.5\mu m$ +Au $0.03\mu m$		
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS		
UNITS mm	◎	SCALE FREE	COUNT ▲ 1	DESCRIPTION OF REVISIONS DIS-F-00021242	DESIGNED TY. EDAGAWA	CHECKED HT. YAMAGUCHI	DATE 20240902
<b>HRS</b> HIROSE ELECTRIC CO., LTD.	APPROVED :KI. AKIYAMA	20100107	DRAWING NO.	EDC-325165-00-00			
	CHECKED :NH. SUGITA	20100107	PART NO.	DM3AT-SF-PEJM5			
	DESIGNED :TY. EDAGAWA	20100107	CODE NO.	CL0609-0031-0-00	▲ 1		
	DRAWN :TY. EDAGAWA	20100107					

5 Drawing for packing (2:1)



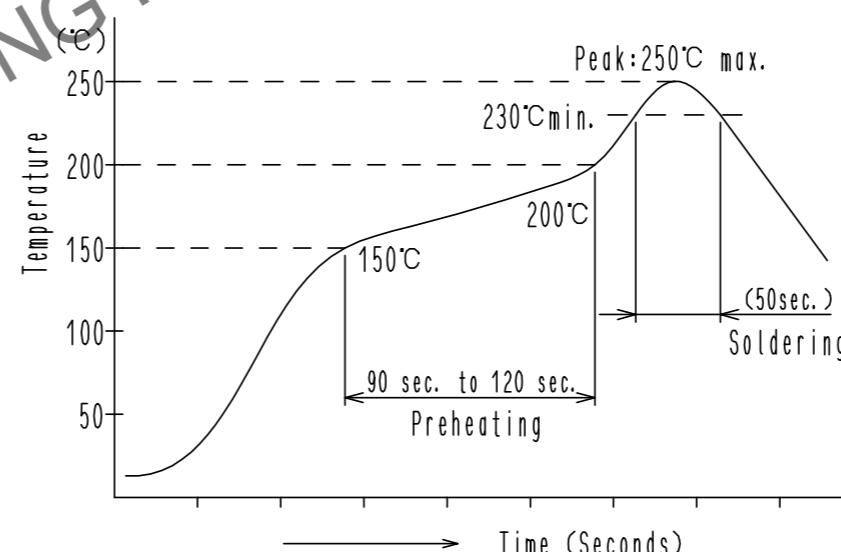
Detail of REEL (1:10)



Notes 5 Drawing type: TAPE and REEL. 1500PCS per REEL.

△ (Delete note)

△ Recommended temperature profile



<Conditions>

Reflow method : Combined far-IR and hot-air reflow  
Reflow atmosphere : Ambient air  
Solder : Cream type Sn/3.0Ag/0.5Cu (M705-GRN360-K2-V made by Senju Kinzoku)  
Board tested : 60×100×1mm glass epoxy  
Metal mask thickness : 0.12mm  
Number of reflow cycles : Two cycles max

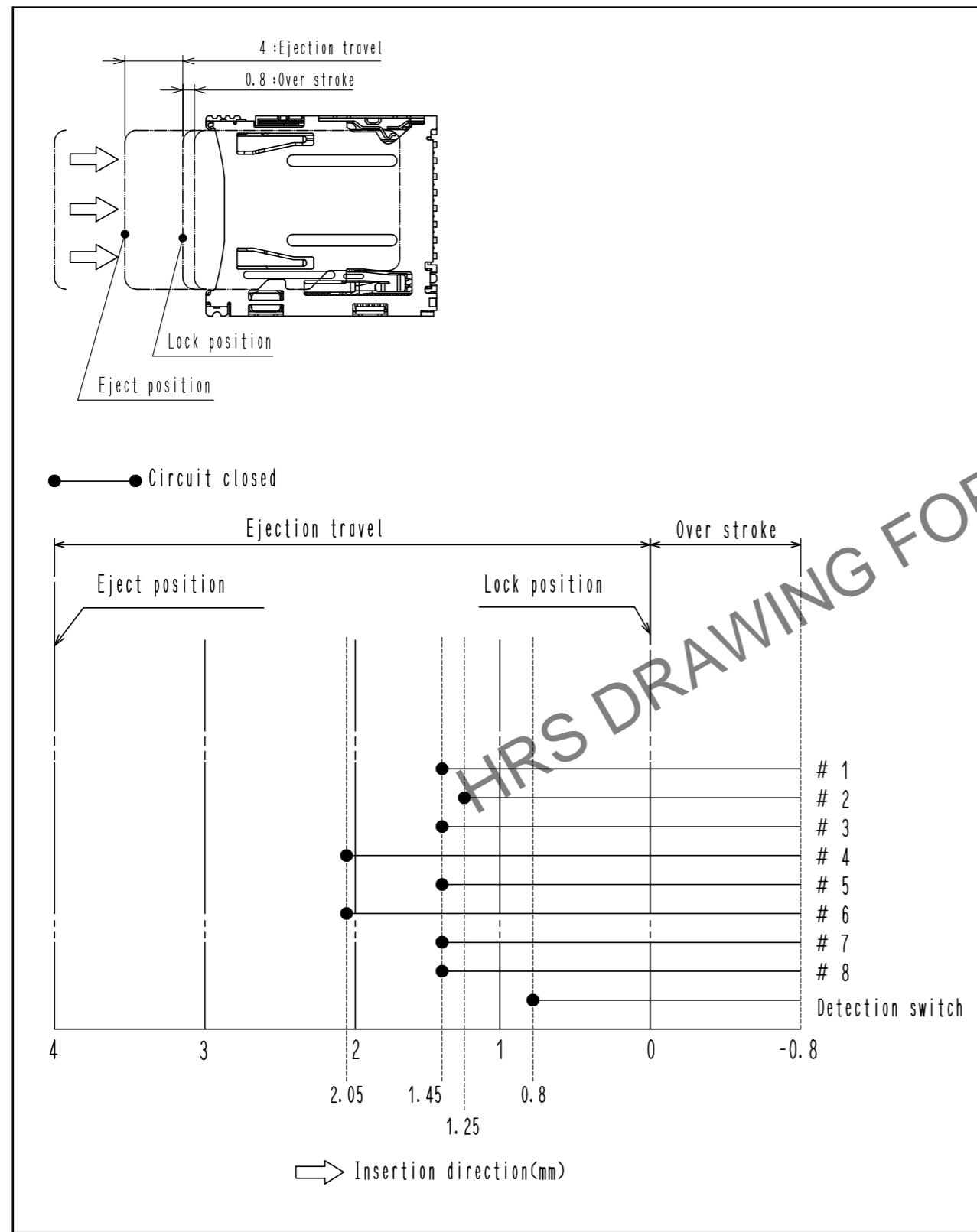
This temperature profile applies to the conditions stated above. Since temperature profiles can vary depending on the type and manufacturer of the cream solder used, as well as board size and other factors including conditions of the parts to be mounted, make sure to check the mounting conditions carefully before use.

<b>HRS</b>	DRAWING NO. EDC-325165-00-00
	PART NO. DM3AT-SF-PEJM5
	CODE NO. CL0609-0031-0-00
	4 2 6

# △ [ Product information and handling instructions ]

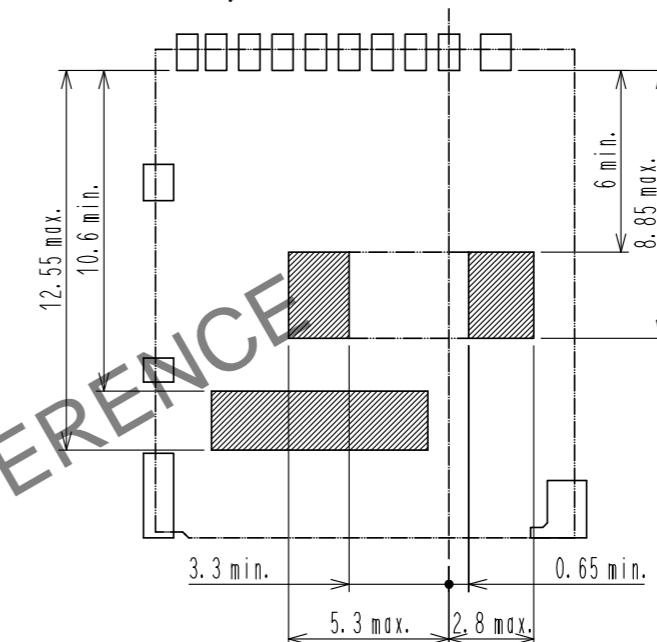
## 1. Contact timing

- Follow the following contact timing chart.



## 2. Area recommended for the application of surface mounting adhesive

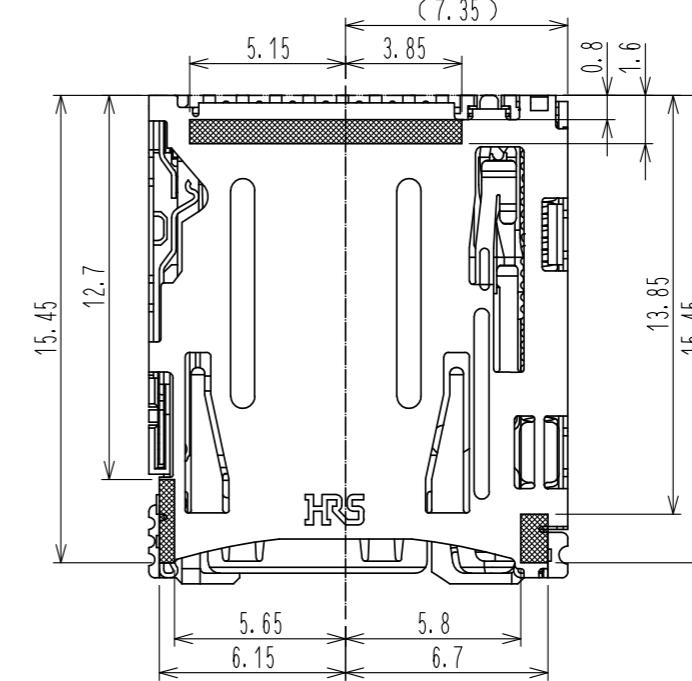
- Make sure to apply adhesives in the applicable areas shown in the drawing below. Avoid the use of adhesives in other areas as this can lead to functional problems. Do not apply excessive amounts of adhesive as this can cause the product to "float" which may in turn cause solder failure. Make sure to use only the smallest amount of adhesive possible.



Recommended adhesive:  
SOMAKOTE IR-010H-3  
(made by Somar Corp.)

## 3. Attachable area on the upper side

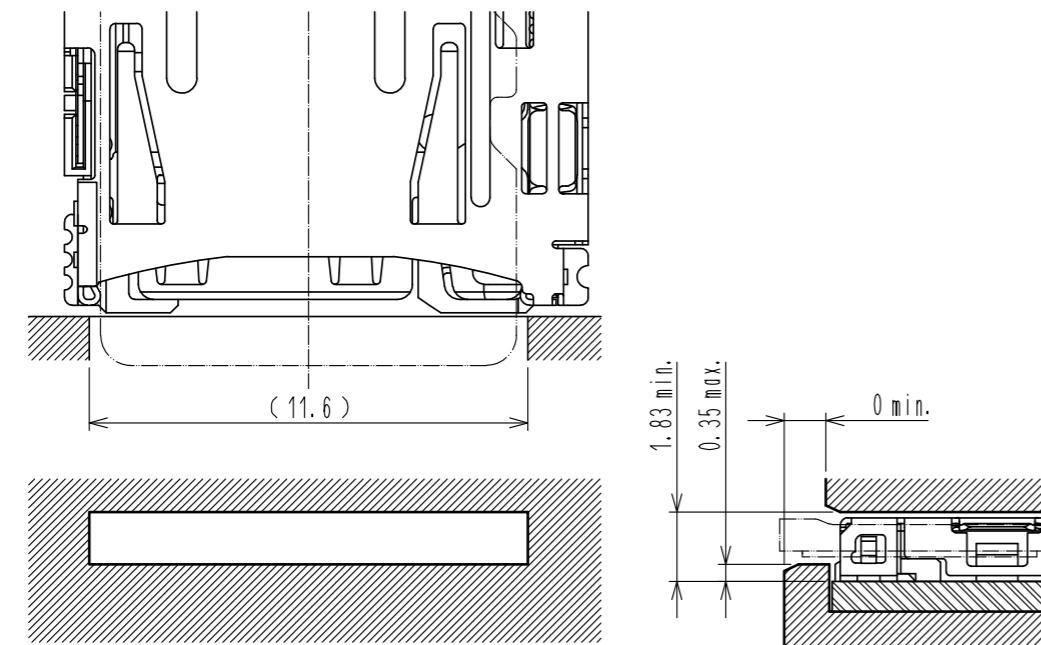
- The shaded area shown in the drawing below designates the area where the product can be pressed on from the upper side using the enclosure.



#### 4. Recommended enclosures

##### ◎ Recommended enclosure dimensions

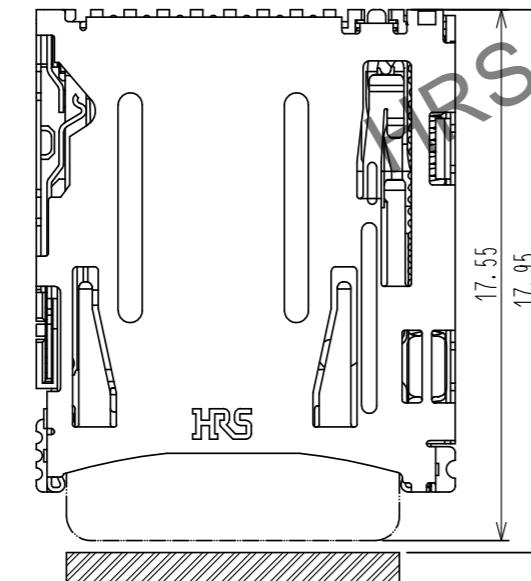
For better card insertability, we recommend enclosure dimensions as shown below.



##### ◎ Recommended dimensions for attaching a cover (lid)

Please install a cover (lid) to prevent the card from falling or becoming misplaced due to unforeseen causes.

The following dimensions are recommended for attaching a cover (lid).



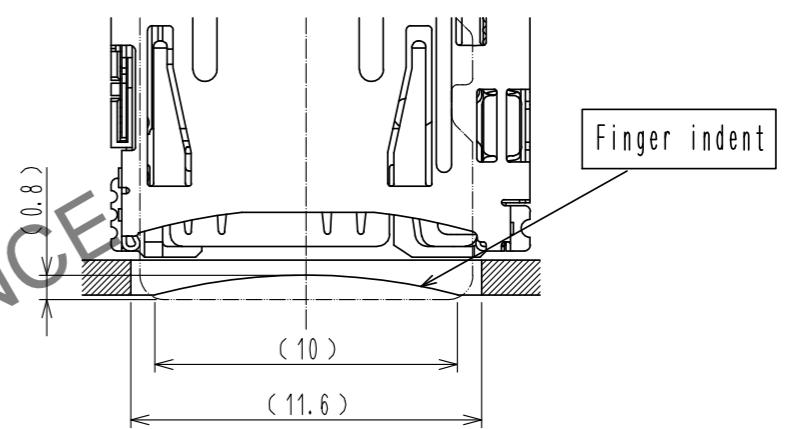
##### ◎ Markings for preventing incorrect card insertion

If you will be displaying markings or instructions to prevent end users from inserting the card incorrectly, please pay extra attention to the text description and the direction of the marking used to indicate the correct direction.

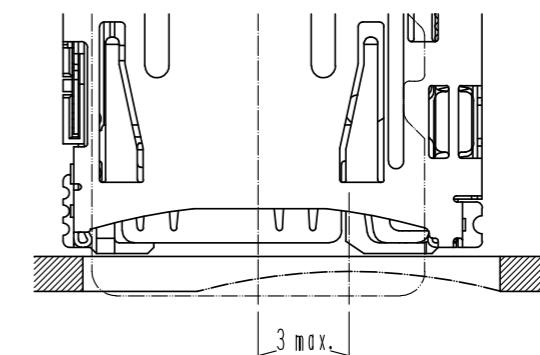
##### ◎ Recommended finger indent

We recommend that you design your enclosure with a "finger indent" as shown in the drawing below to facilitate card withdrawal.

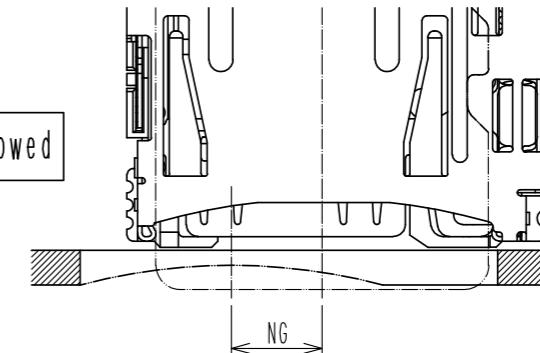
If the center point of the finger indent must be placed off-center of the card, it may be off-center only in the direction shown in the first example shown below. This is to prevent the card from being inserted or withdrawn at an angle.



Off-centering allowed



No off-centering allowed

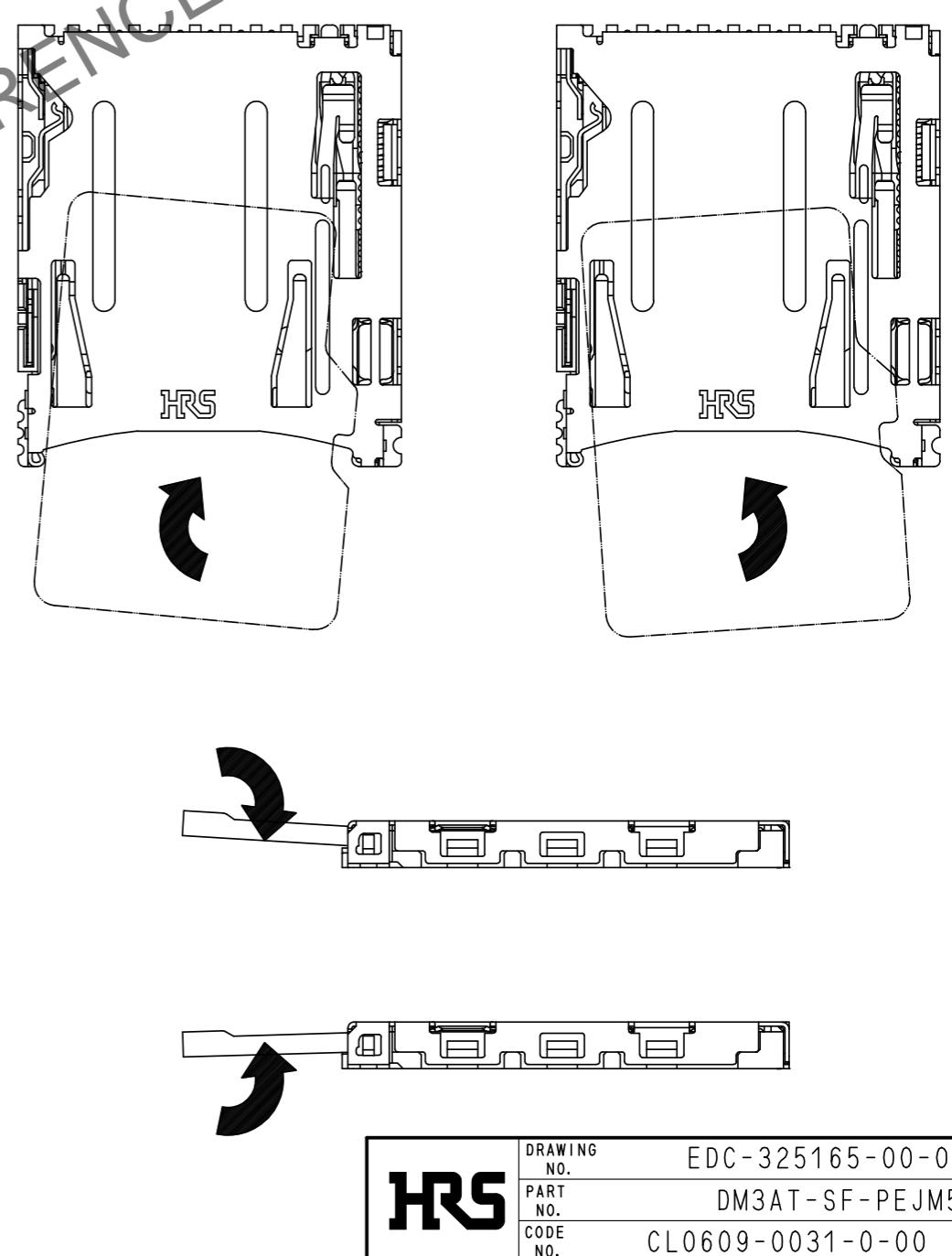
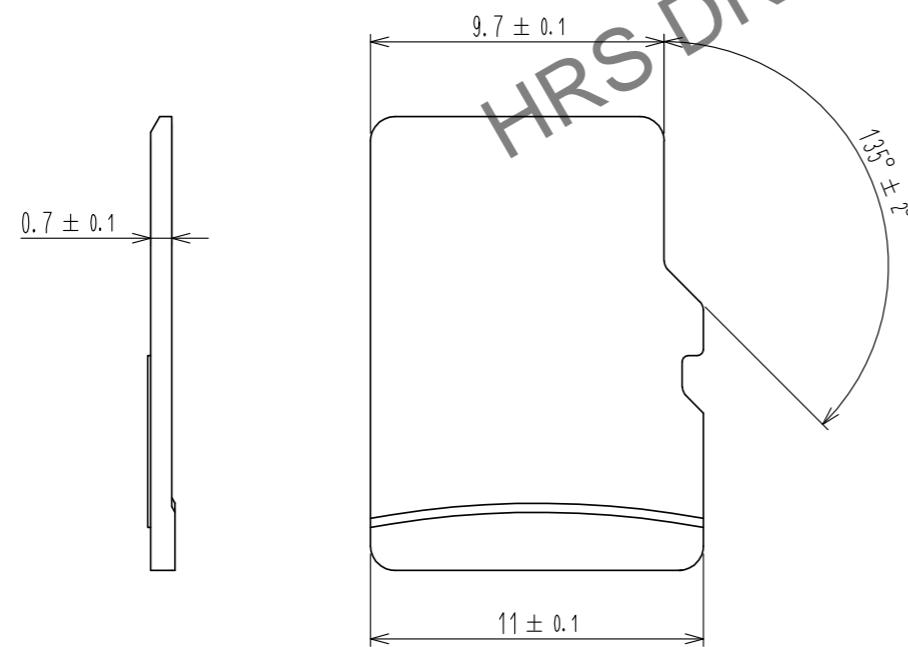


1 | 2 | 3 | 4 | 5 | 6 | 7 | 8

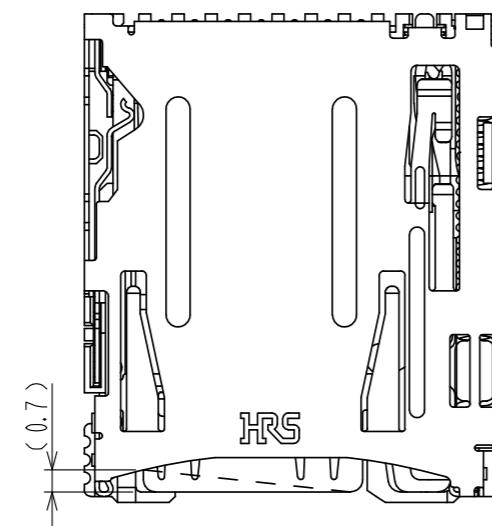
## 5. Reminders

- A (1) This product is equipped with an ejection function.  
Never wash the entire connector as this could lead to problems with this function.  
If it must be washed, wash only the soldered areas and make sure that you do  
no leave any cleaner residues on the connector. Cleaner residues can cause problems  
with card insertion/extraction and electrical performance.
- B (2) Lubricant is applied to this product in order to improve sliding property.  
Lubricant may adhere to the cover due to its appearance, but this does not affect its function.  
Due to the manufacturing process, traces of press oil may remain on the cover,  
but this does not affect its function.
- C (3) If you will be performing card recognition and operating inspections in your  
assembly process, please pay attention to the points listed below.  
If any of these points do not meet requirements, use a new card to perform your inspections.
  - Outer dimensions must be within specifications. Pay particular attention not  
to use products that have become off-spec due to wear.
  - Make sure that there is no severe wear on the pad (base material must not be exposed).
- D (4) Excessive force may cause the connector to fail or become damaged.  
Please handle the connector with care and make sure that it does not deform  
in any way. In particular, avoid the following if you will be performing  
card recognition and operating inspections in your assembly process  
without installing the product to an enclosure.
  - Do not insert or withdraw cards at an angle, whether in a vertical  
or lateral direction.
  - Do not insert or withdraw a partially inserted card by prying it  
in a vertical or lateral direction.

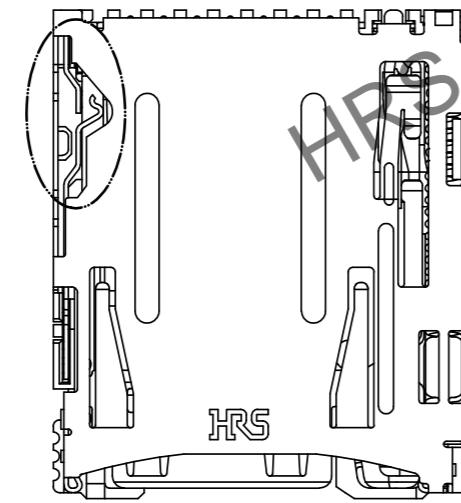
Important outer dimensions  
for microSD CARD standard



(5) Movable parts: The tip of the ejector may be slightly slanted as shown in the drawing but this has no effect on its performance.



(6) The connector's detection contact is exposed due to its low profile design.  
Please handle with care.



(7) This is a connector designed to be mounted on boards.  
Make sure not to use the connector on its own as this could lead to functional problems.

(8) This is a connector for microSD/TransFlash cards. Do not insert other types of cards. Make sure not to insert the card in the wrong direction, at an angle, or forcibly. This product is equipped with a function for preventing users from inserting cards in the wrong direction, but damage may occur to the card and/or connector if the card is forcibly inserted in the wrong direction.

(9) Please do not use a prying motion to withdraw an engaged card.  
This can cause damage to the card and/or connector.

(10) Due to the material used, the surface of a card will be subject to sliding scratches but this will not affect product quality or performance.

(11) Cards are designed to withstand a bending strength of up to 10N.  
Please handle cards with care to prevent damage.

DRAWING NO.	EDC-325165-00-00
PART NO.	DM3AT-SF-PEJM5
CODE NO.	CL0609-0031-0-00
4 6 6 6	